Product Description

WE-3008 is a single component epoxy adhesive designed for use as a reworkable underfill resin for CSP, Flip Chip and BGA.

WE-3008 has high relibility in dropping and thermal shock.

Chemical Type	Epoxy
Appearance	Slight Yellow, Liquid paste
Cure Type	Heat cure
Application	Underfill Resin
Reworkable	Yes

Properties of Uncured material

Specific Gravity @25℃	1.12
Viscosity @25℃, B.F sp.no.4, 20rpm	1,500 ± 500 cps
Pot life @25℃	7 days
Shelf life @below 5℃	6 months

Recommended Curing Conditions

5 minutes at 150℃
20 minutes at 120℃

Properties of Cured material (Cured for 20 minutes @120 ℃)

Density @25℃	1.13 g/㎤
Shrinkage	3.4%
Hardness , Shore-A	64
Tensile Strength , at break	42 N/㎟
Glass Transition Temperature (Tg) by DSC	8 ℃
Coefficient of Thermal Expansion	
α1 (pre Tg)	110×10^{-6}
α2 (post Tg)	215×10^{-6}
Water Absorption , @85℃, RH85%, 500hrs	2.9%
Volume Resistivity	6.8×10^{13} Ω-㎝
Dielectric Constant (1㎒)	4.1

Packing & Storage

Packing	250㎖ , PE Bottle
Storage	Below 5℃